

SPECIFICATION

CUSTOMER: _____

PRODUCT : _____ 声表谐振器

MODEL NO: _____ LT-SR-315-F11

PREPARED: _____ 杨嘉妮 CHECKED: _____ 顾杰

D A T E: _____ 2022-03-10

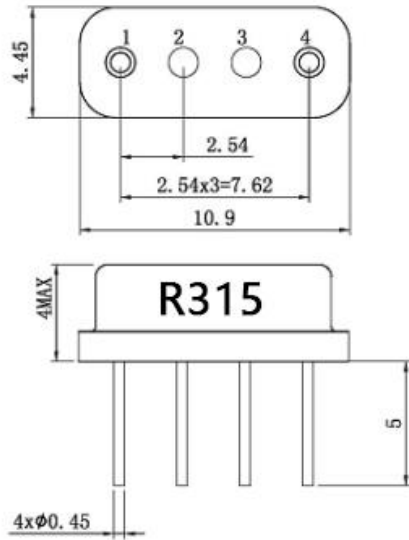
CUSTOMER RECEIVED:		
CHECKED	APPROVED	DATE

版本说明

日期	版本号	修订说明	拟制	审核
2022-03-10	1.0	初版	杨嘉妮	顾杰

SMDCODE.NET
Tra cứu mã IC dẫn và tìm DataSheet

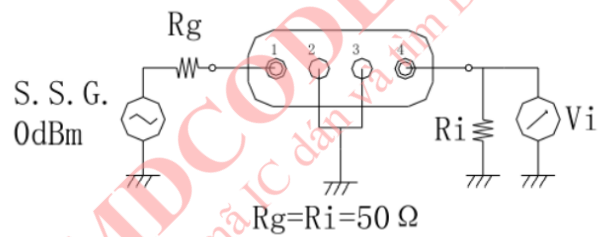
1. Package Dimension (F-11)



Pin	Connection
1	Input
2,3	Ground
4	Output

Marking	
R	SAW resonator
R315	Center Frequency

2. Test Circuit



3. Typical Frequency Response



4. Performance

4-1.Maximum Rating

Rating	Value	Units
CW RF Power Dissipation	+10	dBm
DC Voltage Between Any Two Pins	$\pm 30V$	V
Operation Temperature	-40 to +85	°C
Storage Temperature	-55 to +125	°C

4-2.Electronic Characteristics

Characteristic		Sym	Minimum	Typical	Maximum	Units
Center Frequency (+25°C)	Absolute Frequency	f_c		315.000		MHz
	Tolerance from 315.000MHz	Δf_c		± 75		kHz
Insertion Loss		IL		1.5	2.0	dB
Quality Factor	Unloaded Q	Q_U		17396		
	50 Ω Loaded Q	Q_L		2518		
Temperature Stability	Turnover Temperature	T_O	25	40	55	°C
	Frequency Temperature Coefficient	FTC		0.032		ppm/°C ²
Frequency Aging Absolute Value during the First Year		$ f_A $		≤ 10		ppm/yr
DC Insulation Resistance Between Any Two Pins			1.0			M Ω
RF Equivalent RLC Model	Motional Resistance	R_M		16.9	25	Ω
	Motional Inductance	L_M		148.8		μH
	Motional Capacitance	C_M		1.72		fF
	Pin 1 to Pin 3 Static Capacitance	C_O	2.3	2.6	2.9	pF

CAUTION: Electrostatic Sensitive Device. Observe precautions for handling!

Notes:

1. As a result of the particularity of inner structure of SAW products, it easy to be breakdown by electrostatic, so we should pay attention to ESD protect in the test.
2. Static voltage between signal load and ground may cause deterioration and destruction of the component. Please avoid static voltage.
3. Ultrasonic cleaning may cause deterioration and destruction of the component. Please avoid ultrasonic cleaning.
4. Only leads of component may be soldered. Please avoid soldering another part of component.
5. There is a close relationship between the device's performance and matching network. The specifications of this device are based on the test circuit shown above. L and C values may change depending on board layout. Values shown are intended as a guide only.